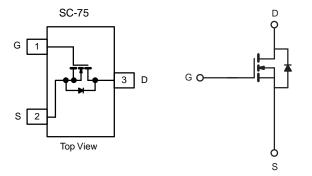


PMR290UNE-VB Datasheet

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^c	Q _g (TYP.)			
20	0.270 at V_{GS} = 4.5 V	0.85				
	0.390 at V _{GS} = 2.5 V	0.70	1.4 nC			



FEATURES

- Trench power MOSFET
- 100 % R_g tested

APPLICATIONS

- Smart phones, tablet PC's - DC/DC converters
 - Boost converters
 - Load switch, OVP switch

ABSOLUTE MAXIMUM RATINGS (T _A =	= 25 °C, unless other	wise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 12		
	T _C = 25 °C		0.85		
	T _C = 70 °C	1.	0.65		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	0.7 ^{a, b}		
	T _A = 70 °C	1	0.6 ^{a, b}	А	
Pulsed Drain Current (t = 300 µs)		I _{DM}	6		
Cartinuaria Causa Duria Dia da Cumant	T _C = 25 °C		0.4		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.3		
	T _C = 25 °C		0.5		
Maulanum David Dissis ation	T _C = 70 °C		0.3		
Maximum Power Dissipation	T _A = 25 °C	P _D	0.4 ^{a, b}		
	T _A = 70 °C		0.3 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	*0		
Soldering Recommendations (Peak Temperature)		260	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient a, d	t ≤ 10 s	R _{thJA}	250	300	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	225	270	0/11	

Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Based on $T_C = 25$ °C.
- d. Maximum under steady state conditions is 360 °C/W.



FREE

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	20	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$\Delta V_{DS}/T_J$ In = 250 µA		32	-	mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			-3	-		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.5	-	1.0	V	
		$V_{DS} = 0 V, V_{GS} = 4.5 V$	-	-	0.1	-	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 12 V$	-	-	± 20		
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	0.1	μΑ	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$	-	-	10	1	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	2	-	-	А	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 1 A	-	0.270	-	- Ω	
	US(on)	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 0.5 \text{ A}$	-	0.390	-		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 1.4 A	-	5	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	105	-	pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	-	23	-		
Reverse Transfer Capacitance	C _{rss}		-	11	-		
Tatal Oata Ohavaa	0	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 1.4 \text{ A}$	-	2.7	4.1	nC	
Total Gate Charge	Qg		-	1.4	2.1		
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 1.4 A	-	0.3	-		
Gate-Drain Charge	Q _{gd}		-	0.5	-		
Gate Resistance	Rg	f = 1 MHz	1.4	7	14	Ω	
Turn-On Delay Time	t _{d(on)}		-	2	4		
Rise Time	t _r	V _{DD} = 15 V, R _L = 13.6 Ω	-	9	18		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1.1$ A, $V_{GEN} = 10$ V, $R_g = 1 \Omega$	-	8	16		
Fall Time	t _f		-	8	16		
Turn-On Delay Time	t _{d(on)}		-	8	16	ns	
Rise Time	t _r	V _{DD} = 15 V, R _L = 13.6 Ω	-	13	20	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1.1$ Å, $V_{GEN} = 4.5$ V, $R_g = 1$ Ω	-	15	23		
Fall Time	t _f		-	6	12		
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	-	-	0.4		
Pulse Diode Forward Current ^a	I _{SM}		-	-	6	A	
Body Diode Voltage	V _{SD}	I _F = 1.1 A	-	0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	8	16	ns	
Body Diode Reverse Recovery Charge	Q _{rr}		-	3	6	nC	
Reverse Recovery Fall Time	ta	$I_F = 1.1 \text{ A}, \text{ dl/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$	-	5	-		
Reverse Recovery Rise Time	t _b			3	-	ns	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

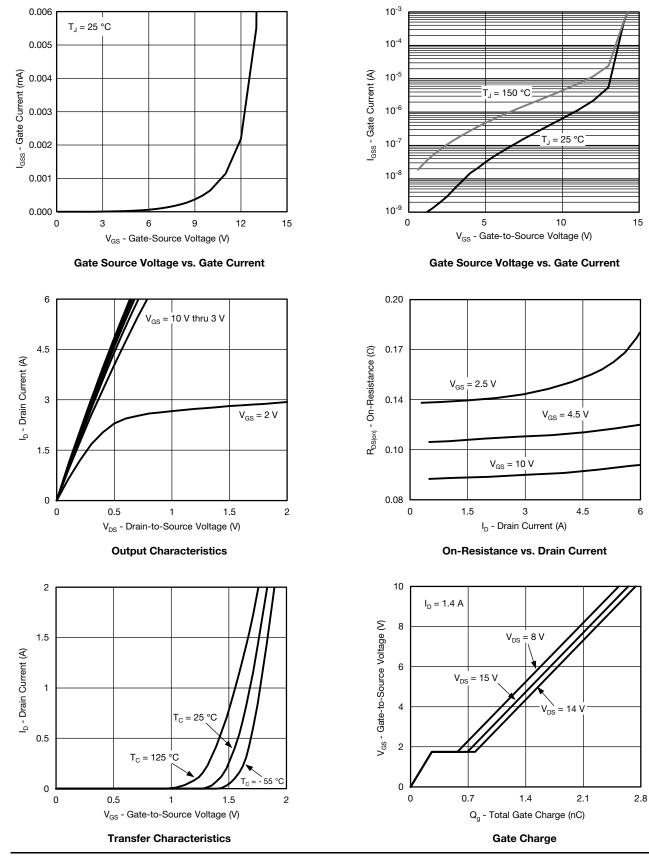
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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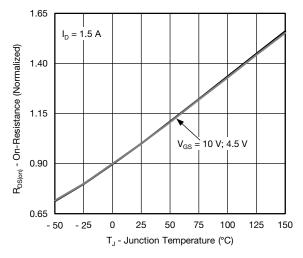




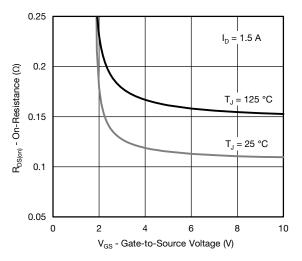




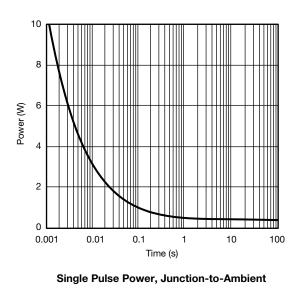
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

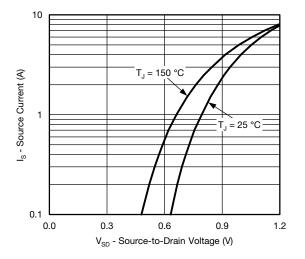


On-Resistance vs. Junction Temperature

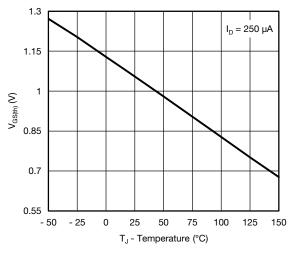


On-Resistance vs. Gate-to-Source Voltage

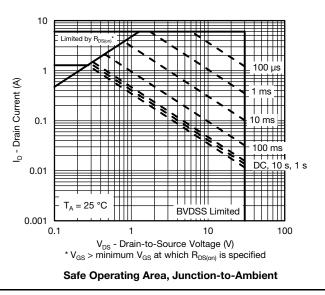




Source-Drain Diode Forward Voltage

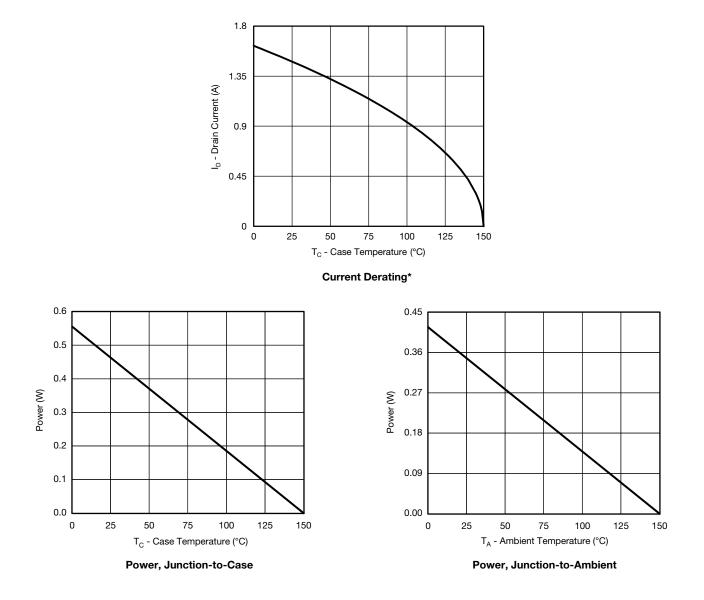








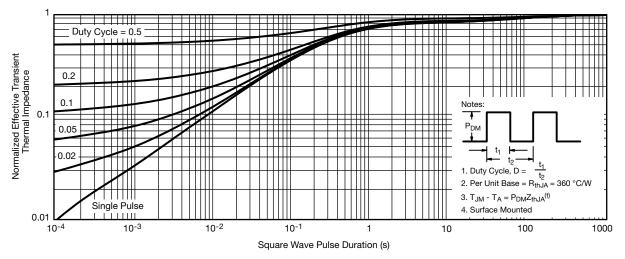
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



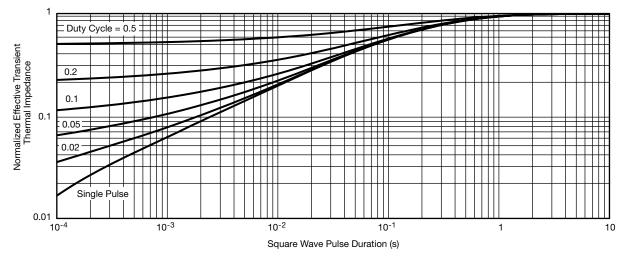
* The power dissipation P_D is based on $T_{J (max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

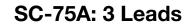


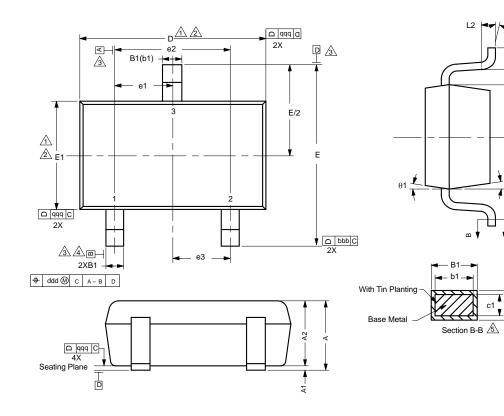
Normalized Thermal Transient Impedance, Junction-to-Foot



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Notes

Dimensions in millimeters will govern.

- Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.
- Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interelead flash, but including any mismatch between the top and bottom of the plastic body.

 $\underline{3}$ Datums A, B and D to be determined 0.10 mm from the lead tip.

4. Terminal positions are shown for reference only.

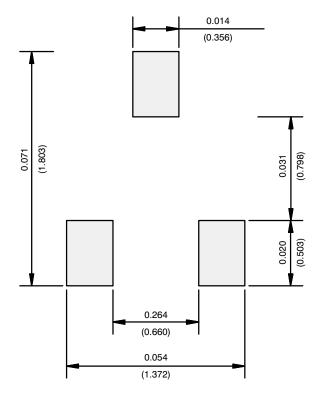
 $\frac{1}{2}$ These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIMENSIONS	TOLERANCES
aaa	0.10
bbb	0.10
ccc	0.10
ddd	0.10

DIM.	n in the second s				
DIM.	MIN.	NOM.	MAX.	NOTE	
А	-	-	0.80		
A ₁	0.00	-	0.10		
A ₂	0.65	0.70	0.80		
B ₁	0.19	-	0.24	5	
b ₁	0.17	-	0.21		
С	0.13	-	0.15	5	
C1	0.10	-	0.12	5	
D	1.48	1.575	1.68	1, 2	
E	1.50	1.60	1.70		
E ₁	0.66	0.76	0.86	1, 2	
e ₁		0.50 BSC			
e ₂					
e ₃	0.50 BSC				
L	0.15	0.205	0.30		
L ₁	0.40 ref.				
L ₂	0.15 BSC				
θ	0°	-	8°		
θ_1	4°	-	10°		



RECOMMENDED MINIMUM PADS FOR SC-75A: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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